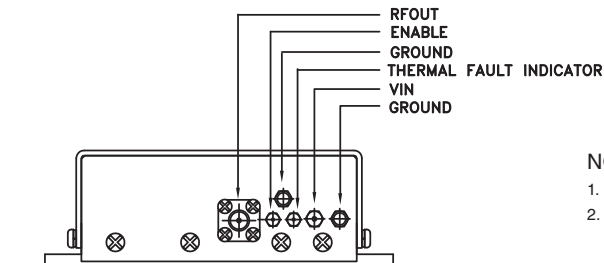
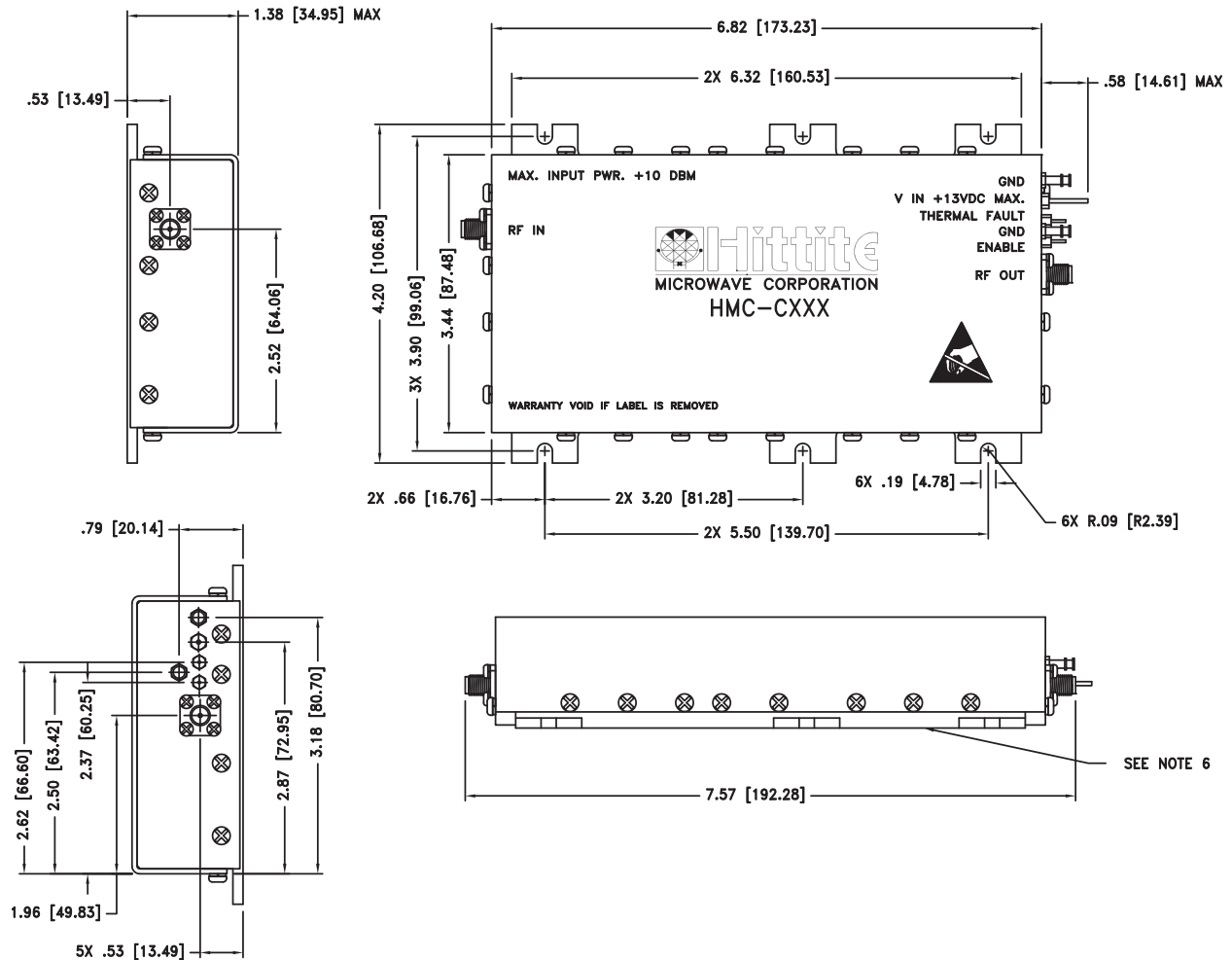


C-7 – CONNECTORIZED HERMETIC MODULE

C-7 Package Outline Drawing



NOTES:

1. MATERIAL: ALUMINUM 6061-T6
2. FINISH
 - a. COVER & END PLATES, CHEMICAL FILM PER MIL-C-5541, CLASS 3
 - b. BASE, TIN
3. RF CONNECTORS, SMA STYLE
4. DIMENSIONS ARE INCHES (MM)
5. TOLERANCES .X±.1 (2.54mm)
.XX±.02 (0.50mm)
6. BASE MUST BE GROUNDED AND MOUNTED TO HEAT SINK CAPABLE OF DISSIPATING 100W (50 °C)

